Jong-Woong Kim

List of Publications by Year
in descending order

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Version: 2024-02-01

		230014	242451
152	3,126	27	47
papers	citations	h-index	g-index

152	152	152	3682
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Ultrareproducible Capacitive Soft Pressure Sensor Using a Selfâ€Integrated Fibrous Network of Urethane Equipped with Dielsâ€“Alder Adducts. Advanced Engineering Materials, 2022, 24, 2100903.	1.6	6
2	Review on Ti3C2-Based MXene Nanosheets for Flexible Electrodes. Electronic Materials Letters, 2022, 18, 256-274.	1.0	16
3	Solution process manufacture of a simple, multifunctional flexible sensor based on capacitance measurement. Nanotechnology, 2021, 32, 265503.	1.3	0
4	Stretchable Inorganic GaN-Nanowire Photosensor with High Photocurrent and Photoresponsivity. ACS Applied Materials & Interfaces, 2021, 13, 22728-22737.	4.0	15
5	One-Way Continuous Deposition of Monolayer MXene Nanosheets for the Formation of Two Confronting Transparent Electrodes in Flexible Capacitive Photodetector. ACS Applied Materials & Interfaces, 2021, 13, 25400-25409.	4.0	11
6	Self-healable, Stretchable, and Highly Luminous Electroluminescent Elastomeric Film Using a Reversibly Crosslinkable Polyurethane. Electronic Materials Letters, 2021, 17, 385-391.	1.0	4
7	UVâ€Curable Adhesive Tapeâ€Assisted Patterning of Metal Nanowires for Ultrasimple Fabrication of Stretchable Pressure Sensor. Advanced Materials Technologies, 2021, 6, 2100776.	3.0	6
8	Development of a Highly Flexible Composite Electrode Comprised of Ti3C2-Based MXene Nanosheets and Ag Nanoparticles. Electronic Materials Letters, 2021, 17, 513.	1.0	7
9	Transparent and stretchable capacitive pressure sensor using selective plasmonic heating-based patterning of silver nanowires. Applied Surface Science, 2021, 561, 149989.	3.1	15
10	Fabrication of a Bending-Insensitive In-Plane Strain Sensor from a Reversible Cross-Linker-Functionalized Silicone Polymer. ACS Applied Materials & Interfaces, 2020, 12, 6516-6524.	4.0	16
11	Water-responsive pressure-sensitive adhesive with reversibly changeable adhesion for fabrication of stretchable devices. Materials and Design, 2020, 195, 108995.	3.3	8
12	Ultrafast Photoinduced Interconnection of Metalâ€“Polymer Composites for Fabrication of Transparent and Stretchable Electronic Skins. ACS Applied Materials & Interfaces, 2020, 12, 39695-39704.	4.0	11
13	Pressure-Sensitive Adhesive with Controllable Adhesion for Fabrication of Ultrathin Soft Devices. ACS Applied Materials & Interfaces, 2020, 12, 40794-40801.	4.0	17
14	Highly transparent, stretchable, and conformable silicone-based strain/pressure-sensitive capacitor using adhesive polydimethylsiloxane. Journal of Alloys and Compounds, 2020, 841, 155773.	2.8	9
15	Selfâ€Healable Capacitive Photodetectors with Stretchability Based on Composite of ZnS:Cu Particles and Reversibly Crosslinkable Silicone Elastomer. Advanced Materials Technologies, 2020, 5, 2000327.	3.0	8
16	Modified Inverted Layer Processing of Ultrathin Touch Sensor Impregnating Ag Nanowires with Both Enlarged Surface Coverage of Conductive Pathways and Ultralow Roughness. Electronic Materials Letters, 2020, 16, 247-254.	1.0	6
17	Self-Integratable, Healable, and Stretchable Electroluminescent Device Fabricated via Dynamic Urea Bonds Equipped in Polyurethane. ACS Applied Materials & Interfaces, 2020, 12, 10949-10958.	4.0	17
18	Interfaceless Strain and Pressureâ€Sensitive Stretchable Capacitor Based on Selfâ€Bonding and Surface Morphology Control of a Reversibly Crosslinkable Silicone Elastomer. Advanced Materials Technologies, 2020, 5, 1900757.	3.0	5

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19	A Behavioralâ€Learned Crossâ€Reactive Sensor Matrix for Intelligent Skin Perception. Advanced Materials, 2020, 32, e2000969.	11.1	61
20	Stretchable photodetector utilizing the change in capacitance formed in a composite film containing semiconductor particles. Composites Science and Technology, 2019, 182, 107773.	3.8	10
21	A UV-responsive pressure sensitive adhesive for damage-free fabrication of an ultrathin imperceptible mechanical sensor with ultrahigh optical transparency. Journal of Materials Chemistry A, 2019, 7, 22588-22595.	5.2	25
22	Transparent, pressure-sensitive, and healable e-skin from a UV-cured polymer comprising dynamic urea bonds. Journal of Materials Chemistry A, 2019, 7, 3101-3111.	5.2	31
23	Motion Artifact Identification and Removal From Wearable Reflectance Photoplethysmography Using Piezoelectric Transducer. IEEE Sensors Journal, 2019, 19, 3861-3870.	2.4	13
24	Conformable, Thin, and Dry Electrode for Electrocardiography Using Composite of Silver Nanowires and Polyvinyl Butyral. Electronic Materials Letters, 2019, 15, 267-277.	1.0	18
25	Improvement in the performance of CIGS solar cells by introducing GaN nanowires on the absorber layer. Journal of Alloys and Compounds, 2019, 779, 643-647.	2.8	9
26	Fabrication and Characterization of a Capacitive Photodetector Comprising a ZnS/Cu Particle/Poly(vinyl butyral) Composite. ACS Applied Materials & Interfaces, 2019, 11, 4416-4424.	4.0	13
27	Transparent and flexible high frequency transmission lines based on composite structure comprising silver nanowires and polyvinyl butyral. Composites Science and Technology, 2018, 159, 25-32.	3.8	9
28	Recyclable thermosetting thermal pad using silicone-based polyurethane crosslinked by Diels-Alder adduct. Applied Surface Science, 2018, 429, 128-133.	3.1	28
29	High-performing flexible and transparent photodetector by using silver nanowire-networks. Materials Research Bulletin, 2018, 97, 244-250.	2.7	26
30	Recyclable patterning of silver nanowire percolated network for fabrication of flexible transparent electrode. Applied Surface Science, 2018, 429, 151-157.	3.1	28
31	Extremely flexible, transparent, and strain-sensitive electroluminescent device based on ZnS:Cu-polyvinyl butyral composite and silver nanowires. Applied Surface Science, 2018, 429, 144-150.	3.1	27
32	Revisiting the thickness reduction approach for near-foldable capacitive touch sensors based on a single layer of Ag nanowire-polymer composite structure. Composites Science and Technology, 2018, 165, 58-65.	3.8	18
33	1.4Â Âµm-Thick Transparent Radio Frequency Transmission Lines Based on Instant Fusion of Polyethylene Terephthalate Through Surface of Ag Nanowires. Electronic Materials Letters, 2018, 14, 599-609.	1.0	5
34	Photo-induced healing of stretchable transparent electrodes based on thermoplastic polyurethane with embedded metallic nanowires. Journal of Materials Chemistry A, 2018, 6, 12420-12429.	5.2	35
35	Electrical Industry. , 2018, , 1449-1482.		0
36	Highly Stretchable and Waterproof Electroluminescence Device Based on Superstable Stretchable Transparent Electrode. ACS Applied Materials & Interfaces, 2017, 9, 5486-5494.	4.0	63

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37	Heterogeneous Configuration of a Ag Nanowire/Polymer Composite Structure for Selectively Stretchable Transparent Electrodes. ACS Applied Materials & Interfaces, 2017, 9, 7505-7514.	4.0	36
38	Silver Nanowire/Colorless-Polyimide Composite Electrode: Application in Flexible and Transparent Resistive Switching Memory. Scientific Reports, 2017, 7, 3438.	1.6	24
39	Flexible InP based quantum dot light-emitting diodes using Ag nanowire-colorless polyimide composite electrode. Journal of Vacuum Science and Technology B:Nanotechnology and Microelectronics, 2017, 35, .	0.6	5
40	Pressure-sensitive strain sensor based on a single percolated Ag nanowire layer embedded in colorless polyimide. Physica B: Condensed Matter, 2017, 514, 8-12.	1.3	6
41	AgNWs networks for high-performing transparent heaters by using NiO window layer. Sensors and Actuators A: Physical, 2017, 267, 8-13.	2.0	14
42	Photo-induced fabrication of Ag nanowire circuitry for invisible, ultrathin, conformable pressure sensors. Journal of Materials Chemistry C, 2017, 5, 9986-9994.	2.7	32
43	Crack-induced Ag nanowire networks for transparent, stretchable, and highly sensitive strain sensors. Scientific Reports, 2017, 7, 7959.	1.6	98
44	Fabrication of substrate-free double-side emitting flexible device based on silver nanowire-polymer composite electrode. Current Applied Physics, 2017, 17, 6-10.	1.1	21
45	A pressure-induced bending sensitive capacitor based on an elastomer-free, extremely thin transparent conductor. Journal of Materials Chemistry A, 2017, 5, 3221-3229.	5.2	26
46	Electrical Industry. , 2017, , 1-34.		0
47	Triarylborylâ€Functionalized Oxadiazole as a Host Material with Electron Transporting Property for Green <scp>PhOLEDs</scp>. Bulletin of the Korean Chemical Society, 2016, 37, 864-870.	1.0	2
48	Mechanically Robust and Healable Transparent Electrode Fabricated via Vapor-Assisted Solution Process. ACS Applied Materials & Interfaces, 2016, 8, 8129-8136.	4.0	17
49	A wearable piezocapacitive pressure sensor with a single layer of silver nanowire-based elastomeric composite electrodes. Journal of Materials Chemistry A, 2016, 4, 10435-10443.	5.2	120
50	Photoresist-assisted fabrication of thermally and mechanically stable silver nanowire-based transparent heaters. Sensors and Actuators A: Physical, 2016, 250, 123-128.	2.0	9
51	Thermally stable and flexible transparent heaters based on silver nanowire-colorless polyimide composite electrode. Current Applied Physics, 2016, 16, 1453-1458.	1.1	14
52	Ultraâ€Facile Fabrication of Stretchable and Transparent Capacitive Sensor Employing Photoâ€Assisted Patterning of Silver Nanowire Networks. Advanced Materials Technologies, 2016, 1, 1600062.	3.0	24
53	Transparent and mechanically robust flexible heater based on compositing of Ag nanowires and conductive polymer. Composites Science and Technology, 2016, 133, 7-14.	3.8	38
54	Critical Role of Dielsâ€"Adler Adducts to Realise Stretchable Transparent Electrodes Based on Silver Nanowires and Silicone Elastomer. Scientific Reports, 2016, 6, 25358.	1.6	25

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55	Electrically and mechanically enhanced Ag nanowires-colorless polyimide composite electrode for flexible capacitive sensor. Applied Surface Science, 2016, 380, 223-228.	3.1	29
56	Preparation of coreâ€“shell microstructures using an electroless plating method. Materials and Design, 2016, 89, 1278-1282.	3.3	9
57	Silver nanowire networks embedded in urethane acrylate for flexible capacitive touch sensor. Applied Surface Science, 2016, 363, 1-6.	3.1	56
58	Extremely rapid and simple healing of a transparent conductor based on Ag nanowires and polyurethane with a Dielsâ€“Alder network. Journal of Materials Chemistry C, 2016, 4, 972-977.	2.7	56
59	Photoenhanced Patterning of Metal Nanowire Networks for Fabrication of Ultraflexible Transparent Devices. ACS Applied Materials & Interfaces, 2016, 8, 480-489.	4.0	66
60	Transparent and flexible film for shielding electromagnetic interference. Materials and Design, 2016, 89, 703-707.	3.3	71
61	The critical role of Ag nanowires in the improvement of conductivity and flexibility of circuits fabricated with hybrid Ag nanopaste. Journal of Materials Science: Materials in Electronics, 2015, 26, 8644-8651.	1.1	9
62	Transparent Electronics: Inverted Layer-By-Layer Fabrication of an Ultraflexible and Transparent Ag Nanowire/Conductive Polymer Composite Electrode for Use in High-Performance Organic Solar Cells (Adv. Funct. Mater. 29/2015). Advanced Functional Materials, 2015, 25, 4743-4743.	7.8	3
63	Microwave Sintering of Silver Nanoink for Radio Frequency Applications. Journal of Nanoscience and Nanotechnology, 2015, 15, 2333-2337.	0.9	11
64	Highly Stretchable and Mechanically Stable Transparent Electrode Based on Composite of Silver Nanowires and Polyurethaneâ€“Urea. ACS Applied Materials & Interfaces, 2015, 7, 15214-15222.	4.0	92
65	Flexible touch sensor with finely patterned Ag nanowires buried at the surface of a colorless polyimide film. RSC Advances, 2015, 5, 42500-42505.	1.7	30
66	Ultra-thin and smooth transparent electrode for flexible and leakage-free organic light-emitting diodes. Scientific Reports, 2015, 5, 9464.	1.6	183
67	Flexible and transparent electrode based on silver nanowires and a urethane acrylate incorporating Dielsâ€“Alder adducts. Materials and Design, 2015, 88, 1158-1163.	3.3	14
68	Inverted Layerâ€Byâ€Layer Fabrication of an Ultraflexible and Transparent Ag Nanowire/Conductive Polymer Composite Electrode for Use in Highâ€Performance Organic Solar Cells. Advanced Functional Materials, 2015, 25, 4580-4589.	7.8	139
69	Intense-pulsed-light irradiation of Ag nanowire-based transparent electrodes for use in flexible organic light emitting diodes. Organic Electronics, 2015, 17, 208-215.	1.4	83
70	Contact-Enhanced Transparent Silver Nanowire Network for All Solution-Based Top-Contact Metal-Oxide Thin-Film Transistors. Journal of Nanoscience and Nanotechnology, 2014, 14, 8158-8162.	0.9	3
71	Solution-Processed Silver Nanowire/Indium-Tin-Oxide Nanoparticle Hybrid Transparent Conductors with High Thermal Stability. Journal of Nanoscience and Nanotechnology, 2014, 14, 9504-9509.	0.9	4
72	Effect of Ag Nanowire Addition Into Nanoparticle Paste on the Conductivity of Ag Patterns Printed by Gravure Offset Method. Journal of Nanoscience and Nanotechnology, 2014, 14, 8808-8812.	0.9	6

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73	Effect of surface treatment on the high-speed drop reliability of Pb-free solder interconnect. Thin Solid Films, 2013, 547, 120-124.	0.8	3
74	Reliability of chip on glass module fabricated with direct printing method. Microelectronic Engineering, 2013, 107, 114-120.	1.1	2
75	Effects of atmospheric pressure plasma surface treatments on the patternability and electrical property of screen-printed Ag nanopaste. Metals and Materials International, 2013, 19, 829-834.	1.8	1
76	Microwave Annealing of Indium Tin Oxide Nanoparticle Ink Patterned by Ink-Jet Printing. Journal of Nanoscience and Nanotechnology, 2013, 13, 6005-6010.	0.9	7
77	Synthesis of Ag Nanowires for the Fabrication of Transparent Conductive Electrode. Journal of Nanoscience and Nanotechnology, 2013, 13, 6244-6248.	0.9	10
78	Characterization of Reliability of Printed Indium Tin Oxide Thin Films. Journal of Nanoscience and Nanotechnology, 2013, 13, 7770-7773.	0.9	1
79	Application of Rapid Milling Technology for Fabrication of SiC Nanoparticles. Journal of Nanoscience and Nanotechnology, 2013, 13, 6064-6068.	0.9	1
80	Fabrication of SiC Nanoparticles by Physical Milling for Ink-Jet Printing. Journal of Nanoscience and Nanotechnology, 2013, 13, 5586-5589.	0.9	2
81	Ductile Fracture Mechanism of Low-Temperature In-48Sn Alloy Joint Under High Strain Rate Loading. Journal of Nanoscience and Nanotechnology, 2012, 12, 3259-3263.	0.9	2
82	Characteristics of Indium–Tin–Oxide (ITO) Glass Re-Used from Old TFT-LCD Panel. Materials Transactions, 2012, 53, 968-972.	0.4	7
83	Evaluation of drop reliability of Snâ€“37Pb solder/Cu joints using a high speed lap-shear test. Microelectronic Engineering, 2012, 91, 147-153.	1.1	15
84	Enhancement of synthetic speed of Ag nanoparticle for electrodes of solar cells by using microwave radiation. Journal of the Korean Physical Society, 2012, 60, 2067-2070.	0.3	1
85	Electrical Characteristics of Printed Ag Nanopaste on Polyimide Substrate. Journal of Nanoscience and Nanotechnology, 2011, 11, 1468-1471.	0.9	4
86	Effect of Sintering Temperature on Electrical Characteristics of Screen-Printed Ag Nanopaste on FR4 Substrate. Journal of Nanoscience and Nanotechnology, 2011, 11, 5915-5920.	0.9	7
87	High Frequency Characteristics of Printed Cu Conductive Circuit. Journal of Nanoscience and Nanotechnology, 2011, 11, 537-540.	0.9	10
88	Synthesis of Cu Nanoparticles with Self-Assembled Monolayers via Inert-Gas Condensation. Journal of Nanoscience and Nanotechnology, 2011, 11, 6020-6024.	0.9	1
89	Flexibility of Silver Conductive Circuits Screen-Printed on a Polyimide Substrate. Journal of Nanoscience and Nanotechnology, 2011, 11, 1493-1498.	0.9	17
90	Improvement of electrical properties of printed ITO thin films by heat-treatment conditions. Current Applied Physics, 2011, 11, S202-S205.	1.1	13

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91	Characteristics of eco-friendly synthesized SiO2 dielectric nanoparticles printed on Si substrate. Microelectronic Engineering, 2011, 88, 797-801.	1.1	1
92	Effect of heat treatment on physical and electrical characteristics of conductive circuits printed on Si substrate. Microelectronic Engineering, 2011, 88, 791-796.	1.1	1
93	Introduction of an Electroless-Plated Ni Diffusion Barrier in Cu/Sn/Cu Bonding Structures for 3D Integration. Journal of the Electrochemical Society, 2011, 159, H85-H89.	1.3	14
94	Electrical Industry. , 2011, , 1289-1313.		1
95	Characteristics of Printed Thin Films Using Indium Tin Oxide (ITO) Ink. Materials Transactions, 2010, 51, 1905-1908.	0.4	15
96	Failure mechanism of Pb-bearing and Pb-free solder joints under high-speed shear loading. Metals and Materials International, 2010, 16, 7-12.	1.8	29
97	Characterization of direct patterned Ag circuits for RF application. Microelectronic Engineering, 2010, 87, 379-382.	1.1	27
98	Physical and Electrical Properties of SiO2Layer Synthesized by Eco-Friendly Method. Japanese Journal of Applied Physics, 2010, 49, 05EA02.	0.8	4
99	Effects of the Concentration of Indium-tin-oxide (ITO) Ink on the Characteristics of Directly-printed ITO Thin Films. Journal of the Korean Physical Society, 2010, 57, 1794-1798.	0.3	7
100	FAILURE BEHAVIORS OF FLIP CHIP SOLDER JOINTS UNDER VARIOUS LOADING CONDITIONS OF HIGH-SPEED SHEAR TEST. International Journal of Modern Physics B, 2009, 23, 1809-1815.	1.0	3
101	Fabrication and electrical characterization of through-Si-via interconnect for 3-D packaging. Journal of Micro/ Nanolithography, MEMS, and MOEMS, 2009, 8, 013040.	1.0	5
102	Failure behaviors of BGA solder joints under various loading conditions of high-speed shear test. Journal of Materials Science: Materials in Electronics, 2009, 20, 17-24.	1.1	22
103	Electromigration Behavior in Sn-37Pb and Sn-3.0Ag-0.5Cu Flip-Chip Solder Joints under High Current Density. Journal of Electronic Materials, 2009, 38, 70-77.	1.0	18
104	Mechanical Property Evaluation of Sn-3.0A-0.5Cu BGA Solder Joints Using High-Speed Ball Shear Test. Journal of Electronic Materials, 2009, 38, 2489-2495.	1.0	20
105	Solder joint reliability in flip chip package with surface treatment of ENIG under thermal shock test. Metals and Materials International, 2009, 15, 655-660.	1.8	11
106	Reliability of Au bump flip chip packages with adhesive materials using four-point bending test. International Journal of Adhesion and Adhesives, 2009, 29, 650-655.	1.4	13
107	Transmission property of flip chip package with adhesive interconnection for RF applications. Microelectronic Engineering, 2009, 86, 314-320.	1.1	4
108	Ultrasonic Bonding of Electrodes of Rigid and Flexible Printed Circuit Boards with Non-Conductive Film (NCF). Journal of Adhesion, 2009, 85, 341-350.	1.8	2

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109	Electrical Characterization of Screen-Printed Conductive Circuit with Silver Nanopaste. Japanese Journal of Applied Physics, 2009, 48, 06FD14.	0.8	14
110	Study on Fabrication of 3-Dimensional Stacked Chip Package with Anisotropic Conductive Film. Journal of Welding and Joining, 2009, 27, 32-37.	0.3	0
111	Lap joint properties of FSWed dissimilar formed 5052 Al and 6061 Al alloys with different thickness. Journal of Materials Science, 2008, 43, 3296-3304.	1.7	73
112	Reliability of Conductive Adhesives as a Pb-free Alternative in Flip-Chip Applications. Journal of Electronic Materials, 2008, 37, 9-16.	1.0	17
113	Mechanical and Electrical Properties of Cu/Sn-3.5Ag/Cu Ball Grid Array (BGA) Solder Joints after Multiple Reflows. Journal of Electronic Materials, 2008, 37, 118-124.	1.0	17
114	Mechanical reliability evaluation of Sn-37Pb solder joint using high speed lap-shear test. Microelectronic Engineering, 2008, 85, 1967-1970.	1.1	25
115	Effect of high-speed loading conditions on the fracture mode of the BGA solder joint. Microelectronics Reliability, 2008, 48, 1882-1889.	0.9	25
116	Effect of displacement rate on bump shear properties of electroplated solder bumps in flip-chip packages. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2008, 483-484, 620-624.	2.6	5
117	Thermal degradation of anisotropic conductive film joints under temperature fluctuation. International Journal of Adhesion and Adhesives, 2008, 28, 314-320.	1.4	11
118	Mechanical reliability of Sn-rich Auâ€“Sn/Ni flip chip solder joints fabricated by sequential electroplating method. Microelectronics Reliability, 2008, 48, 1857-1863.	0.9	28
119	Effect of Bonding Conditions on Conduction Behavior of Anisotropic Conductive Film Interconnection. Metals and Materials International, 2008, 14, 373-379.	1.8	8
120	Effect of reflow numbers on the interfacial reaction and shear strength of flip chip solder joints. Journal of Alloys and Compounds, 2008, 458, 253-260.	2.8	27
121	Effect of boron content in electroless Niâ€“B layer on plating layer properties and soldering characteristics with Snâ€“Ag solder. Journal of Alloys and Compounds, 2008, 466, 73-79.	2.8	24
122	Analysis of Failure Mechanism in Anisotropic Conductive and Non-Conductive Film Interconnections. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 65-73.	1.4	24
123	Microwave Performance of Flip Chip Interconnects With Anisotropic and Non-conductive Films. Journal of Adhesion Science and Technology, 2008, 22, 1339-1354.	1.4	2
124	Evaluation of Thermal and Hygro-Thermal Behaviors of Flip Chip Packages With a Non-conductive Paste. Journal of Adhesion Science and Technology, 2008, 22, 1355-1364.	1.4	0
125	Electrical characterization of adhesive flip chip interconnects for microwave application. Journal of Micro/ Nanolithography, MEMS, and MOEMS, 2008, 7, 023007.	1.0	2
126	Effect of Atmospheric Pressure Plasma Treatment on Transverse Ultrasonic Bonding of Gold Flip-Chip Bump on Glass Substrate. Japanese Journal of Applied Physics, 2008, 47, 4309-4313.	0.8	8

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127	Mechanical Reliability Evaluation of Sn-37Pb/Cu and Sn-37Pb/ENIG Solder Joints by using High Speed Lap-shear Test. , 2008, , .		0
128	Electrical Characterization of Electronic Package. Journal of Welding and Joining, 2008, 26, 17-23.	0.3	0
129	Characterization of Failure Behaviors in Anisotropic Conductive Interconnection. Materials Transactions, 2007, 48, 1070-1078.	0.4	12
130	Transmission property of adhesive interconnect for high frequency applications. , 2007, , .		0
131	Thermal and hygroscopic reliability of flip-chip packages with an anisotropic conductive film. Journal of Adhesion Science and Technology, 2007, 21, 1071-1087.	1.4	1
132	Reliability of adhesive interconnections for application in display module. Microelectronic Engineering, 2007, 84, 2691-2696.	1.1	27
133	Interfacial reaction and joint reliability of fine-pitch flip-chip solder bump using stencil printing method. Microelectronic Engineering, 2007, 84, 2640-2645.	1.1	6
134	Effect of bonding force on the reliability of the flip chip packages employing anisotropic conductive film with reflow process. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2007, 452-453, 267-272.	2.6	23
135	Design of Solder Joint Structure for Flip Chip Package with an Optimized Shear Test Method. Journal of Electronic Materials, 2007, 36, 690-696.	1.0	4
136	Behavior of Anisotropic Conductive Film Joints Bonded with Various Forces under Temperature Fluctuation. Journal of Electronic Materials, 2007, 36, 1199-1205.	1.0	5
137	Characteristic analysis of electroless Ni plating layer for electronic packaging. Surface and Interface Analysis, 2006, 38, 440-443.	0.8	4
138	Reexamination of the solder ball shear test for evaluation of the mechanical joint strength. International Journal of Solids and Structures, 2006, 43, 1928-1945.	1.3	27
139	Effects of bonding pressure on the thermo-mechanical reliability of ACF interconnection. Microelectronic Engineering, 2006, 83, 2335-2340.	1.1	25
140	Evaluation of displacement rate effect in shear test of Snâ€“3Agâ€“0.5Cu solder bump for flip chip application. Microelectronics Reliability, 2006, 46, 535-542.	0.9	31
141	Investigations of the test parameters and bump structures in the shear test of flip chip solder bump. Thin Solid Films, 2006, 504, 405-409.	0.8	18
142	Evaluation of solder joint reliability in flip chip package under thermal shock test. Thin Solid Films, 2006, 504, 426-430.	0.8	21
143	Optimization of shear test for flip chip solder bump using 3-dimensional computer simulation. Microelectronic Engineering, 2005, 82, 554-560.	1.1	8
144	Reliability evaluations of flip chip package under thermal shock test. Microelectronic Engineering, 2005, 82, 575-580.	1.1	11

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145	Effect of aging conditions on interfacial reaction and mechanical joint strength between Snâ€“3.0Agâ€“0.5Cu solder and Niâ€“P UBM. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2005, 121, 204-210.	1.7	47
146	Characterization of the shear test method with low melting point Inâ€“48Sn solder joints. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2005, 397, 145-152.	2.6	30
147	Mechanical strength test method for solder ball joint in BGA package. Metals and Materials International, 2005, 11, 121-129.	1.8	17
148	Evaluation of solder joint reliability in flip-chip packages during accelerated testing. Journal of Electronic Materials, 2005, 34, 1550-1557.	1.0	33
149	Correlation between the interfacial reaction and mechanical joint strength of the flip chip solder bump during isothermal aging. Journal of Materials Science: Materials in Electronics, 2005, 16, 603-609.	1.1	10
150	Solid state interfacial reaction and joint strength of Snâ€“37Pb solder with Niâ€“P under bump metallization in flip chip application. Journal of Alloys and Compounds, 2005, 395, 80-87.	2.8	31
151	Experimental and finite element analysis of the shear speed effects on the Snâ€“Ag and Snâ€“Agâ€“Cu BGA solder joints. Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing, 2004, 371, 267-276.	2.6	75
152	The Joint Characteristics of Friction Stir Welded AZ91D Magnesium Alloy. Materials Transactions, 2003, 44, 917-923.	0.4	78